

GSM4948W

60V P-Channel Enhancement Mode MOSFET

Product Description

GSM4948W, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

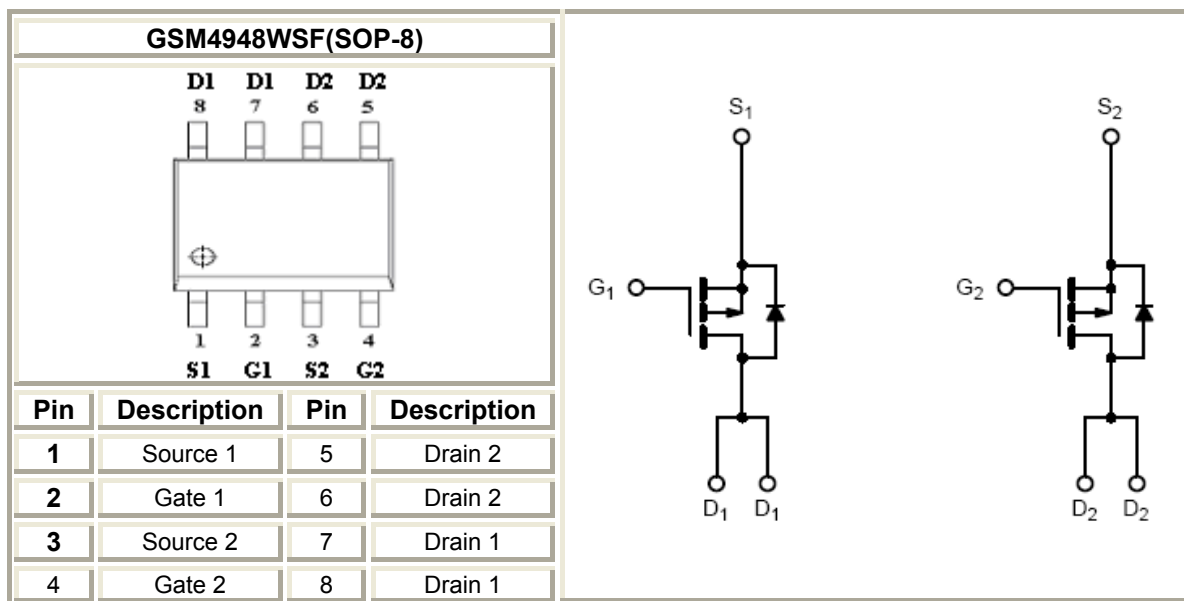
Features

- -60V/-4.0A, $R_{DS(ON)}=100m\Omega@V_{GS}=-10V$
- -60V/-3.0A, $R_{DS(ON)}=112m\Omega@V_{GS}=-4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- SOP-8 package design

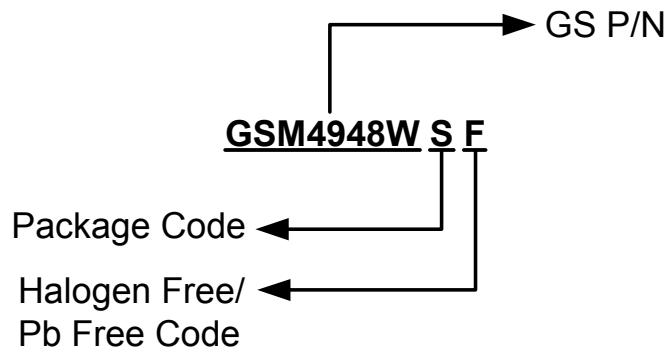
Applications

- Backlight Inverter for LCD Display
- Full Bridge DC/DC Converter
- Load Switch
- CCFL Inverter

Packages & Pin Assignments

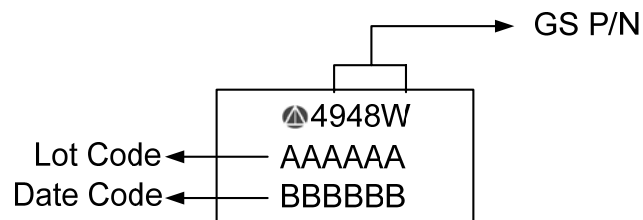


Ordering Information



| Part Number | Package | Quantity Reel |
|-------------|---------|---------------|
| GSM4948WSF | SOP-8 | 2500 PCS |

Marking Information



Absolute Maximum Ratings

(T_A=25°C unless otherwise noted)

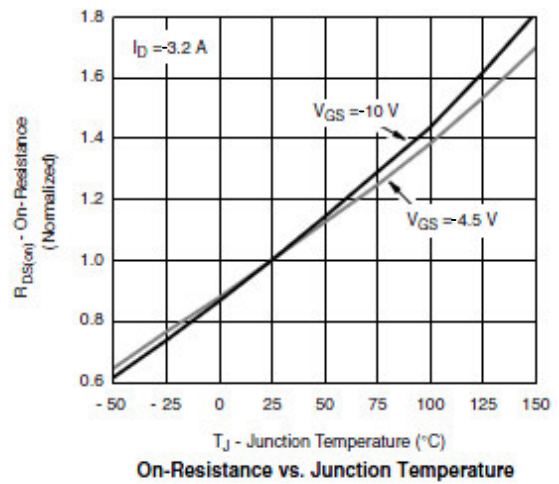
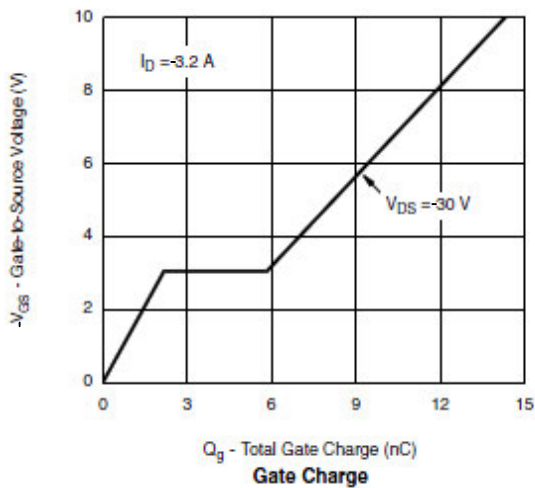
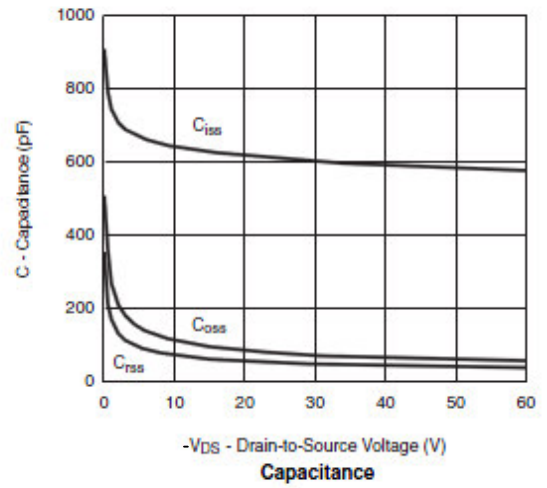
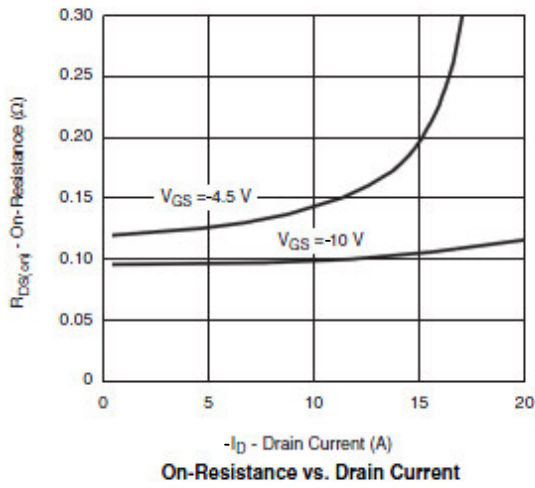
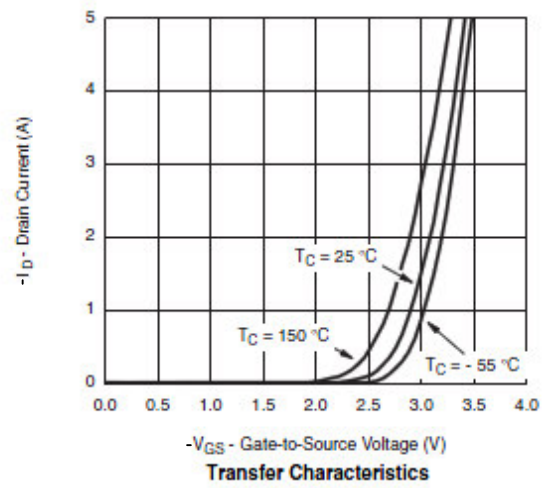
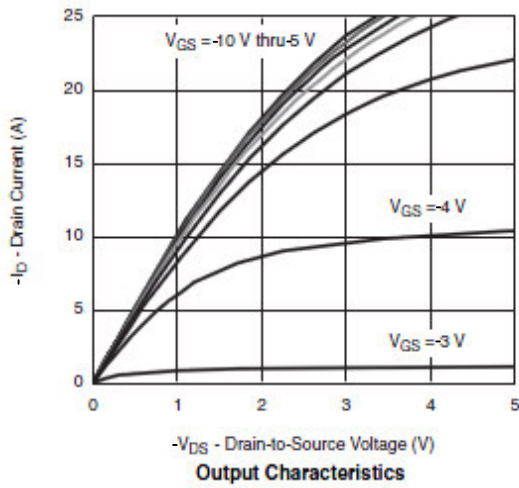
| Symbol | Parameter | Typical | Unit |
|------------------|---|----------------------|-------|
| V _{DSS} | Drain-Source Voltage | -60 | V |
| V _{GSS} | Gate-Source Voltage | ±20 | V |
| I _D | Continuous Drain Current(T _J =150°C) | T _A =25°C | -4.0 |
| | | T _A =70°C | -3.0 |
| I _{DM} | Pulsed Drain Current | -20 | A |
| I _S | Continuous Source Current(Diode Conduction) | -1.7 | A |
| P _D | Power Dissipation | T _A =25°C | 2.8 |
| | | T _A =70°C | 1.8 |
| T _J | Operating Junction Temperature | 150 | °C |
| T _{STG} | Storage Temperature Range | -55/150 | °C |
| R _{θJA} | Thermal Resistance-Junction to Ambient | 62.5 | °C/ W |

Electrical Characteristics

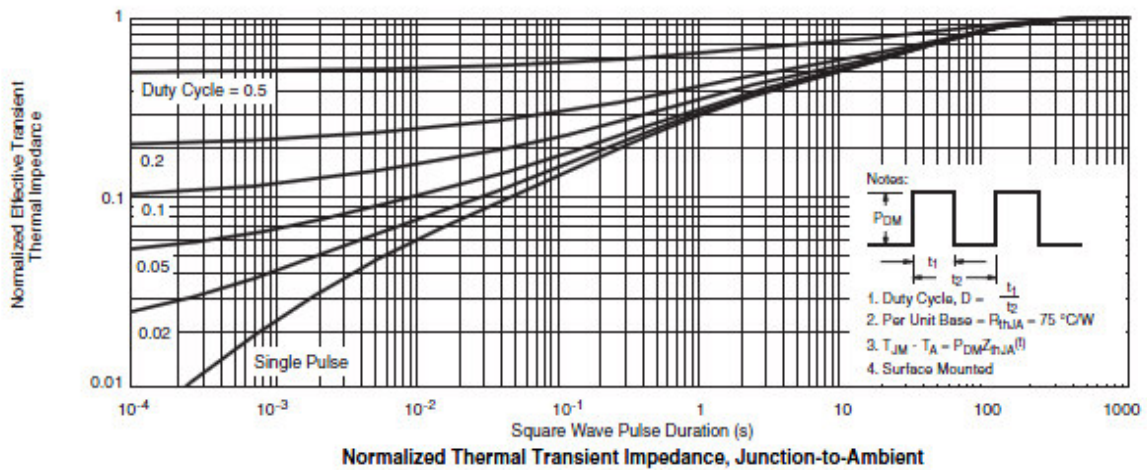
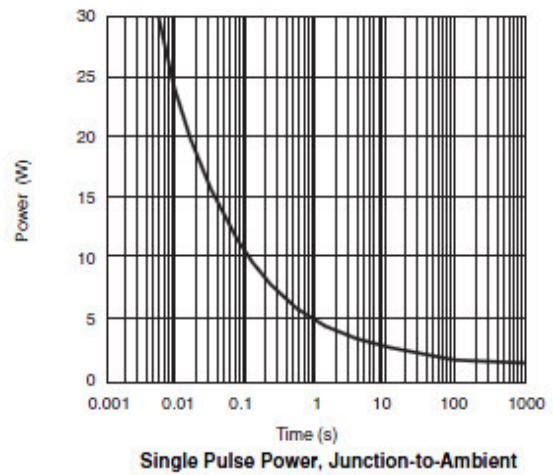
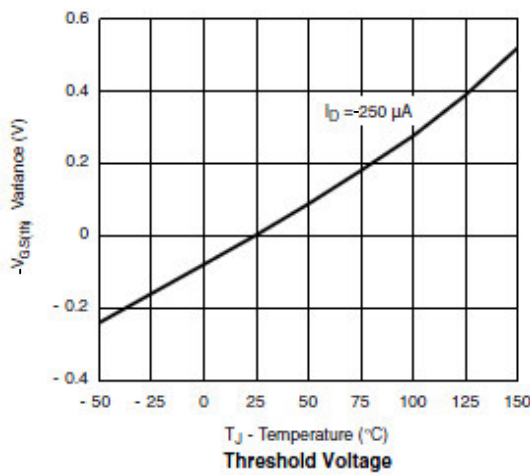
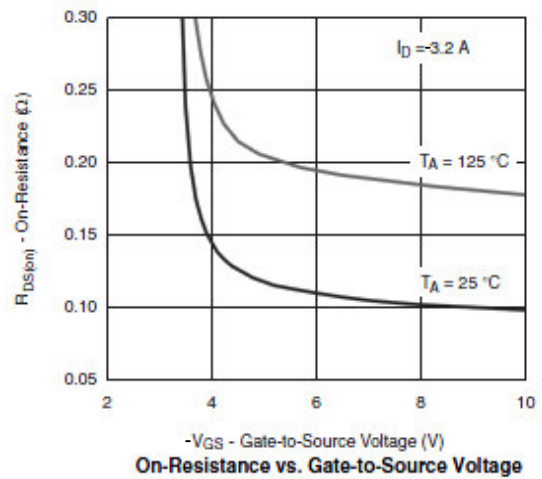
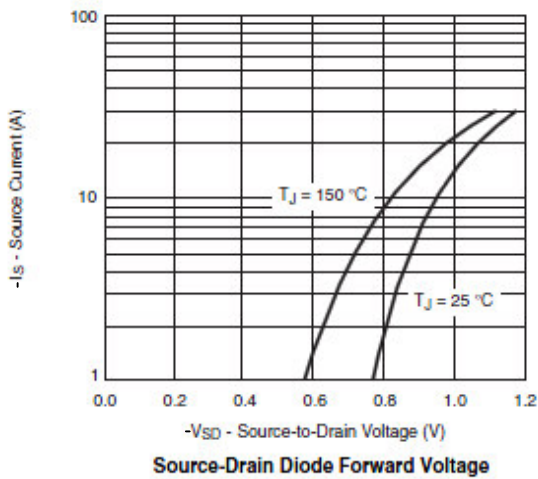
($T_A=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---------------------------------|--|------|------|-----------|------------|
| Static | | | | | | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -60 | | | V |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -0.8 | | -2.5 | |
| I_{GSS} | Gate Leakage Current | $V_{DS}=0V, V_{GS}=\pm 20V$ | | | ± 100 | nA |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-48V, V_{GS}=0V$ | | | -1 | uA |
| | | $V_{DS}=-48V, V_{GS}=0V, T_J=85^\circ\text{C}$ | | | -20 | |
| $I_{D(on)}$ | On-State Drain Current | $V_{DS}\leq -5V, V_{GS}=-10V$ | -20 | | | A |
| $R_{DS(on)}$ | Drain-Source On-Resistance | $V_{GS}=-10V, I_D=-4.0A$ | | 92 | 100 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-3.0A$ | | 100 | 112 | |
| g_{fs} | Forward Transconductance | $V_{DS}=-15V, I_D=-3.2A$ | | 12 | | S |
| V_{SD} | Diode Forward Voltage | $I_S=-2A, V_{GS}=0V$ | | -0.8 | -1.2 | V |
| Dynamic | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS}=-30V, V_{GS}=0V, f=1\text{MHz}$ | | 900 | | pF |
| C_{oss} | Output Capacitance | | | 90 | | |
| C_{rss} | Reverse Transfer Capacitance | | | 40 | | |
| Q_g | Total Gate Charge | $V_{DS}=-30V, V_{GS}=-10V, I_D=-4.0A$ | | 12 | 20 | nC |
| Q_{gs} | Gate-Source Charge | | | 2.5 | | |
| Q_{gd} | Gate-Drain Charge | | | 3.5 | | |
| $t_{d(on)}$ | Turn-On Time | $V_{DD}=-30V, R_L=7.5\Omega, I_D=-3.0A, V_{GEN}=-10V, R_G=3\Omega$ | | 10 | 20 | ns |
| T_r | | | | 6 | 10 | |
| $t_{d(off)}$ | Turn-Off Time | | | 30 | 45 | |
| T_f | | | | 12 | 25 | |

Typical Performance Characteristics

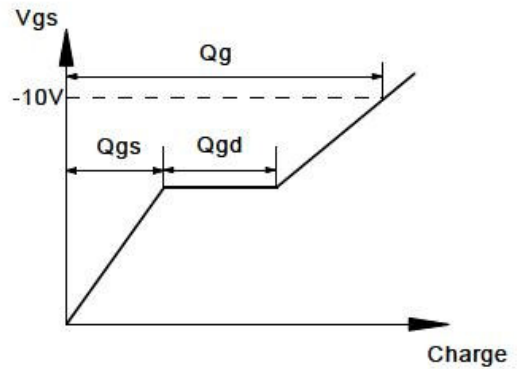
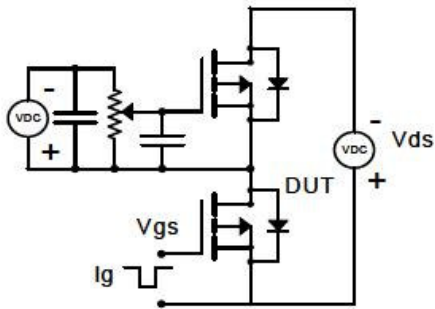


Typical Performance Characteristics (continue)

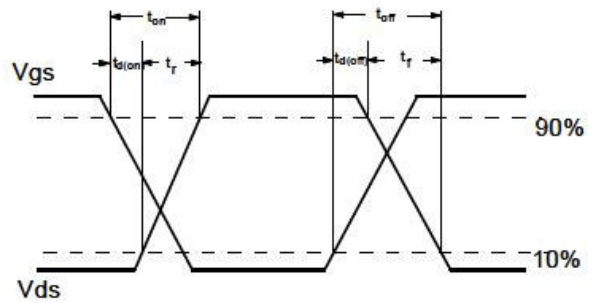
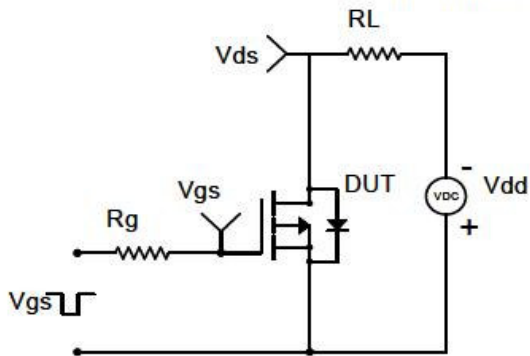


Typical Performance Characteristics (continue)

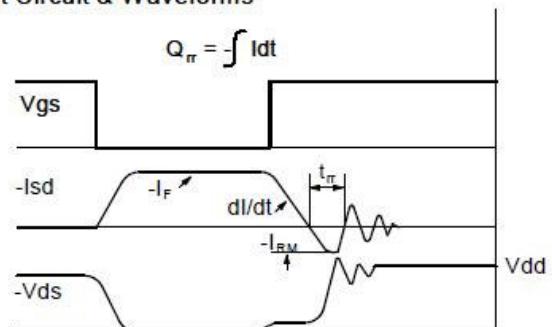
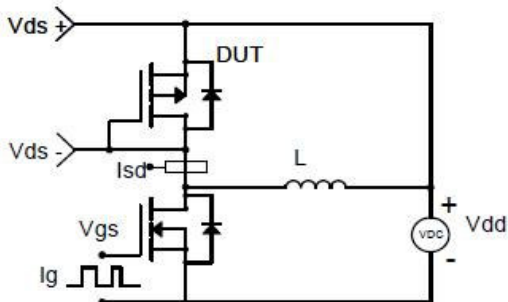
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

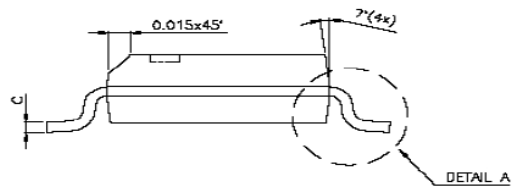
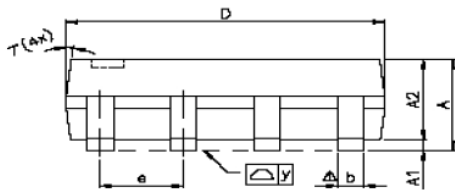
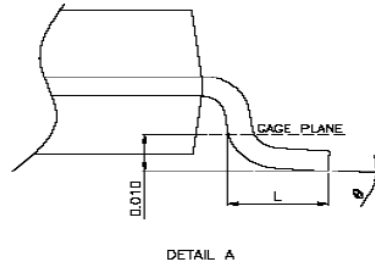
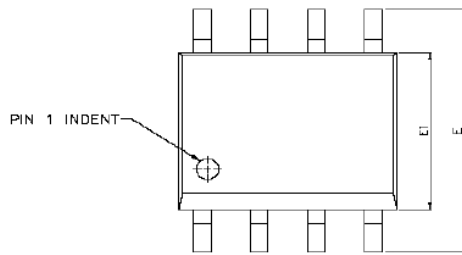


Diode Recovery Test Circuit & Waveforms



Package Dimension

SOP-8 PLASTIC PACKAGE










| Dimensions | | | | | | |
|------------|-------------|------|-------|--------|-------|--------|
| SYMBOL | Millimeters | | | Inches | | |
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.47 | 1.60 | 1.73 | 0.058 | 0.063 | 0.068 |
| A1 | 0.10 | - | 0.25 | 0.004 | - | 0.010 |
| A2 | - | 1.45 | - | - | 0.057 | - |
| b | 0.33 | 0.41 | 0.51 | 0.013 | 0.016 | 0.020 |
| C | 0.19 | 0.20 | 0.25 | 0.0075 | 0.008 | 0.0098 |
| D | 4.80 | 4.85 | 4.95 | 0.189 | 0.191 | 0.195 |
| E | 5.80 | 6.00 | 6.20 | 0.228 | 0.236 | 0.244 |
| E1 | 3.80 | 3.90 | 4.00 | 0.150 | 0.154 | 0.157 |
| e | - | 1.27 | - | - | 0.050 | - |
| L | 0.38 | 0.71 | 1.27 | 0.015 | 0.028 | 0.050 |
| Δy | - | - | 0.076 | - | - | 0.003 |
| θ | 0° | - | 8° | 0° | - | 8° |



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